



| | | |
|-------------------------------------|--|--|
| Title of Change: | To convert H11AD9X-5660 series + MCT9001x series from Single to Matrix Leadframe | |
| Proposed first ship date: | 11 April 2019 | |
| Contact information: | Contact your local ON Semiconductor Sales Office or khaicheong.yau@onsemi.com | |
| Samples: | Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. | |
| Additional Reliability Data: | Contact your local ON Semiconductor Sales Office or changkit.mok@onsemi.com | |
| Type of notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com> | |
| Change Part Identification: | It will be identified by implementation datecode. | |
| Change Category: | <input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____ | |
| Change Sub-Category(s): | <input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____ | |
| Sites Affected: | ON Semiconductor Sites: None | External Foundry/Subcon Sites: Liteon Bangkok |

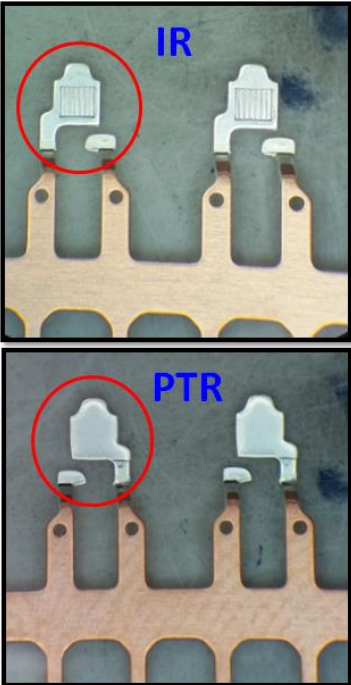
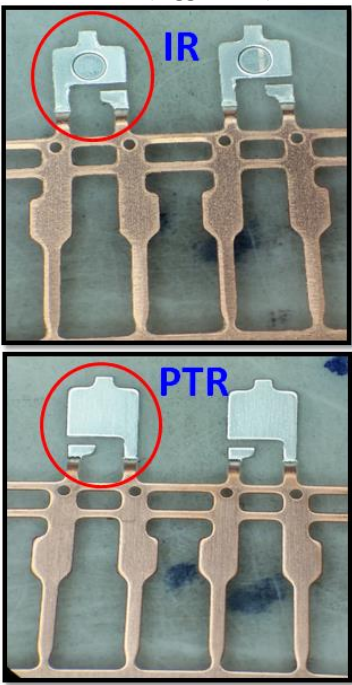


Description and Purpose:

The Matrix unit will be in

1. Laser mark instead of inked mark
2. Bigger DAP
3. Has an unique mold ID stamp

Reason : Leadframe vendor would not want to continue with the support of non-matrix leadframe

| | Before Change Description | After Change Description |
|---------------|--|---|
| LeadFrame | Single  | Matrix (Bigger DAP)  |
| Mold Compound | Without Mold ID | With Mold ID |

| | From | To |
|------------------------|----------|------------|
| Product marking change | Ink Mark | Laser Mark |



Reliability Data Summary:

DEVICE: MCT9001
PACKAGE: PDIP 8 (Black Package)

| Test | Specification | Condition | Interval | Results |
|----------|---------------------|--------------------------|-------------|---------|
| HTOL | JESD22-A108 | Ta=100°C, biased | 1008 hours | 0/240 |
| HTSL | JESD22-A103 | Ta= 150°C, unbiased | 1008 hours | 0/240 |
| PC | J-STD-020 JESD-A113 | MSL 1@260°C | - | 0/480 |
| TC + PC | JESD22-A104 | Ta= -55°C to +125°C | 1000 cycles | 0/240 |
| THB + PC | JESD22-A101 | Ta=85°C / 85% RH, biased | 1008 hours | 0/240 |
| RSH | JESD22- B106 | Ta = 265C, 10 sec | - | 0/30 |
| SD | JSTD002 | Ta = 245C, 10 sec | - | 0/10 |

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.

| Part Number | Qualification Vehicle |
|-------------|-----------------------|
| MCT9001 | MCT9001 |
| MCT9001S | |
| MCT9001SD | |